R223.424.000

Series: MMBX

**PACKAGING** 

Unit	Other
'W' option	Contact us

#### **SPECIFICATION**

#### **ELECTRICAL CHARACTERISTICS**

Impedance  $50 \Omega$ 

Frequency 0-12.4 GHz

VSWR 1.065 + 0,0000 x F(GHz) Maxi Insertion loss 0.12  $\sqrt{F(GHz)}$  dB Maxi

RF leakage - ( 100 - F(GHz)) dB Maxi

Voltage rating - ( 100 - F(GHz)) di

Dielectric withstanding voltage 1000 Veff mini Insulation resistance 1000 M $\Omega$  mini

#### **ENVIRONMENTAL**

Operating temperature -55/+155 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

#### **OTHER CHARACTERISTICS**

Assembly instruction NA

Others:

to 6 GHz

Interface MMBX only,up to  $2.5\ \mathrm{GHz}$ 

PCB to PCB -45dB up to 2.5 GHz

Mated pair height 6.7mm

### MECHANICAL CHARACTERISTICS

Center contact retention

Standard 100

Axial force – Mating end
Axial force – Opposite end

10 N mini
10 N mini

Torque NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3050** g

**Issue:** 0736 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

RADIALL®

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# SOLDER PROCEDURE OF MMBX RECEPTACLE IN INDUSTRIAL ENVIRONMENT

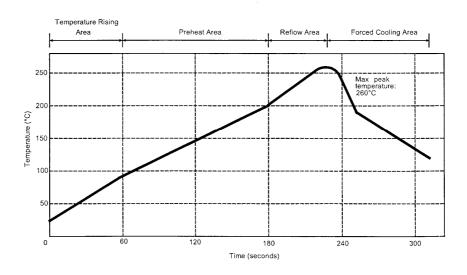
- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
  - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

A video camera is recommended for positioning of the component.

Adhesive agents must not be used on the receptacle.

- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged.
- 5. Verification of solder joints and position of the component by visual inspection.

#### TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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necessary.

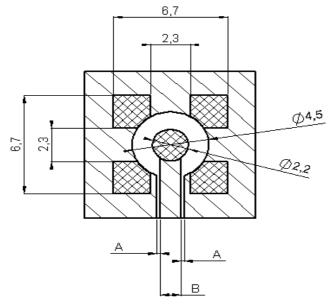


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## MMBX SERIES INFORMATIONS

## **PCB**



#### **COPLANAR LINE**

Pattern and signal are on the same side The material of PCB is epoxy resin (FR4). (Er = 4.6)

The solder resist should be printed Except for the land pattern on the PCB



Pattern



Land for solder paste

## APPLICATION 75Ω

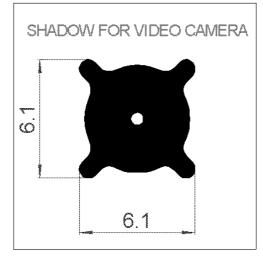
WITH B = 0.55mm

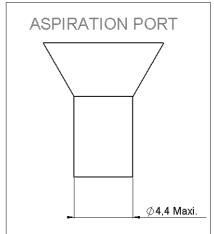
PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,350
1,0	0,360
1,2	0,365
1,6	0,375

#### $\mathsf{APPLICATION}\ 50\Omega$

WITH B = 1,2mm

<u>'</u>	
PCB thickness (mm)	Coplanar ligne A (mm)
0,8	0,190
1,0	0,200
1,2	0,205
16	0.210





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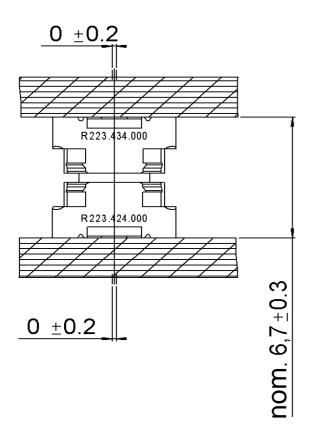
necessary

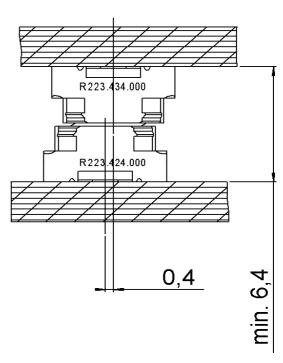


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## **MMBX SERIES INFORMATIONS**





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